

	Type	Hits	Search Text	DBs	Time Stamp
1	BRS	274	(semiconductor or die or chip or IC) and solder with offset	USPAT	2004/03/29 15:43
2	BRS	17	(semiconductor or die or chip or IC) and solder with offset and solder with (lower or faster) near (melt\$3 or dissolv\$3)	USPAT	2004/03/29 13:52
3	BRS	3777	(semiconductor or die or chip or IC) and (contacts or terminal or pad) with offset	USPAT	2004/03/29 15:52
4	BRS	210	(semiconductor or die or chip or IC) and (contacts or terminal or pad) with offset and different with material with (contacts or terminals or pad)	USPAT	2004/03/29 15:44
5	BRS	1523	((semiconductor or die or chip or IC) and (contacts or terminal or pad) with offset) and temperature	USPAT	2004/03/29 17:53
6	BRS	274	257/779 and (semiconductor or die or chip or IC) and (contacts or terminal or pad) with temperature	USPAT	2004/03/29 18:29
7	BRS	256	257/779 and (contacts or terminal or pad) with support\$3	USPAT	2004/03/29 18:29
8	BRS	311	257/779 and (contacts or terminal or pad or solder) with support\$3	USPAT	2004/03/29 18:36
9	BRS	736	257/778 and (contacts or terminal or pad or solder) with support\$3	USPAT	2004/03/29 18:37
10	BRS	561	(257/778 and (contacts or terminal or pad or solder) with support\$3) not (257/779 and (contacts or terminal or pad or solder) with support\$3)	USPAT	2004/03/29 18:37
11	BRS	1	"4875617".PN.	USPAT	2004/03/29 18:47
12	BRS	1	"4930001".PN.	USPAT	2004/03/29 18:47
13	BRS	1	"5017738".PN.	USPAT	2004/03/29 18:47

	Type	Hits	Search Text	DBs	Time Stamp
14	BRS	1	"5186379".PN.	USPAT	2004/03/29 18:47
15	BRS	1	"5264699".PN.	USPAT	2004/03/29 18:47
16	BRS	1	"5308980".PN.	USPAT	2004/03/29 18:47
17	BRS	1	"5468655".PN.	USPAT	2004/03/29 18:48
18	BRS	1	"5611481".PN.	USPAT	2004/03/29 18:48
19	BRS	1	"5646426".PN.	USPAT	2004/03/29 18:48
20	BRS	1	"5814891".PN.	USPAT	2004/03/29 18:48
21	BRS	1	"5897341".PN.	USPAT	2004/03/29 18:49
22	BRS	1	"5902686".PN.	USPAT	2004/03/29 18:49
23	BRS	1	"6329608".PN.	USPAT	2004/03/29 18:49
24	BRS	1	"6340113".PN.	USPAT	2004/03/29 18:49
25	BRS	2050	(semiconductor or die or chip or IC) and low with solder and high with solder	USPAT	2004/03/31 18:44
26	BRS	2050	((semiconductor or die or chip or IC) and low with solder and high with solder) and 257/\$.ccls.	USPAT	2004/03/31 17:38
27	BRS	1121	((semiconductor or die or chip or IC) and low with solder and high with solder) and 257/\$.ccls.	USPAT	2004/03/31 18:22
28	BRS	929	((semiconductor or die or chip or IC) and low with solder and high with solder) not (((semiconductor or die or chip or IC) and low with solder and high with solder) and 257/\$.ccls.)	USPAT	2004/03/31 18:23
29	BRS	3206	(semiconductor or die or chip or IC) and (low or lower or "low-melting") with solder and (high or higher) with solder	USPAT	2004/03/31 18:45

	Type	Hits	Search Text	DBs	Time Stamp
30	BRS	760	((semiconductor or die or chip or IC) and (low or lower or "low-melting") with solder and (high or higher) with solder) and (big or bigger or large or larger) with solder and (small or smaller or other or regular) with solder	USPAT	2004/03/31 18:48
31	BRS	336	((semiconductor or die or chip or IC) and (low or lower or "low-melting") with solder and (high or higher) with solder) and (big or bigger or large or larger) with solder same (low or lower or "low-melting") with solder	USPAT	2004/03/31 18:50
32	BRS	139	((semiconductor or die or chip or IC) and (low or lower or "low-melting") with solder and (high or higher) with solder) and (big or bigger or large or larger) with solder same (low or lower or "low-melting") with solder with (melt\$3 or molten or temperature)	USPAT	2004/03/31 21:19
33	BRS	68	"5646828"	USPAT	2004/03/31 20:29
34	BRS	5	"5646828" and first adj chip and second adj chip	USPAT	2004/03/31 20:30
35	BRS	183	257/777 and first adj chip and second adj chip	USPAT	2004/03/31 20:30
36	BRS	52	(257/777 or 257/778 or 257/779 or 257/780 or 257/781) and (big or bigger or large or larger) with solder same (low or lower or "low-melting") with solder with (melt\$3 or molten or temperature)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/31 21:21

	Type	Hits	Search Text	DBs	Time Stamp
37	BRS	15	(257/723 or 257/724 or 257/685 or 257/686) and (big or bigger or large or larger) with solder same (low or lower or "low-melting") with solder with (melt\$3 or molten or temperature)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/ 31 21:22
38	BRS	17	(257/690 or 257/700) and (big or bigger or large or larger) with solder same (low or lower or "low-melting") with solder with (melt\$3 or molten or temperature)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/ 31 21:22